



**THE DATASHEET OF
BSD816SNH6327XTSA1**

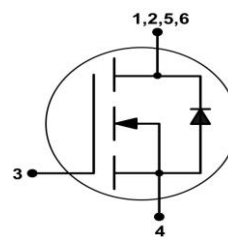
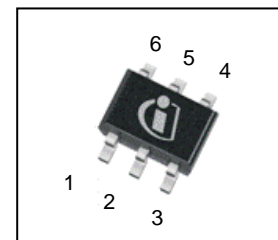


OptiMOS™2 Small-Signal-Transistor
Features

- N-channel
- Enhancement mode
- Ultra Logic level (1.8V rated)
- Avalanche rated
- Qualified according to AEC Q101
- 100% lead-free; RoHS compliant
- Halogen-free according to IEC61249-2-21


Product Summary

V_{DS}	20	V
$R_{DS(on),max}$	$V_{GS}=2.5\text{ V}$	160
	$V_{GS}=1.8\text{ V}$	240
I_D	1.4	A


PG-SOT363


Type	Package	Tape and Reel Information	Marking	Lead Free	Packing
BSD816SN	PG-SOT363	H6327: 3000 pcs/ reel	XAs	Yes	Non dry

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_A=25\text{ °C}$	1.4	A
		$T_A=70\text{ °C}$	1.1	
Pulsed drain current	$I_{D,pulse}$	$T_A=25\text{ °C}$	5.6	
Avalanche energy, single pulse	E_{AS}	$I_D=1.4\text{ A}$, $R_{GS}=25\ \Omega$	3.7	mJ
Reverse diode dv/dt	dv/dt	$I_D=1.4\text{ A}$, $V_{DS}=16\text{ V}$, $di/dt=200\text{ A}/\mu\text{s}$, $T_{j,max}=150\text{ °C}$	6	kV/ μs
Gate source voltage	V_{GS}		± 8	V
Power dissipation ¹⁾	P_{tot}	$T_A=25\text{ °C}$	0.5	W
Operating and storage temperature	T_j , T_{stg}		-55 ... 150	°C
ESD Class		JESD22-A114 -HBM	0 (<250V)	
Soldering Temperature			260 °C	
IEC climatic category; DIN IEC 68-1			55/150/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - ambient	R_{thJA}	minimal footprint ¹⁾	-	-	250	K/W
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Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified
Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$	20	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=3.7\text{ }\mu\text{A}$	0.3	0.55	0.95	
Drain-source leakage current	I_{DSS}	$V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	-	1	μA
		$V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ °C}$	-	-	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=8\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=1.8\text{ V}, I_D=0.44\text{ A}$	-	158	240	$\text{m}\Omega$
		$V_{GS}=2.5\text{ V}, I_D=1.4\text{ A}$	-	112	160	
Transconductance	g_{fs}	$ V_{DS} >2 I_D R_{DS(on)max}, I_D=1.1\text{ A}$		4.8	-	S

¹⁾ Performed on 40mm² FR4 PCB. The traces are 1mm wide 70 μm thick and 20mm long; they are present on both sides of the PCB.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=10\text{ V},$ $f=1\text{ MHz}$	-	126	180	pF
Output capacitance	C_{oss}		-	47	67	
Reverse transfer capacitance	C_{rss}		-	7	10	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=10\text{ V}, V_{GS}=2.5\text{ V},$ $I_D=1.4\text{ A}, R_{G,ext}=6\ \Omega$	-	5.3	-	ns
Rise time	t_r		-	9.0	-	
Turn-off delay time	$t_{d(off)}$		-	11	-	
Fall time	t_f		-	2.2	-	

Gate Charge Characteristics

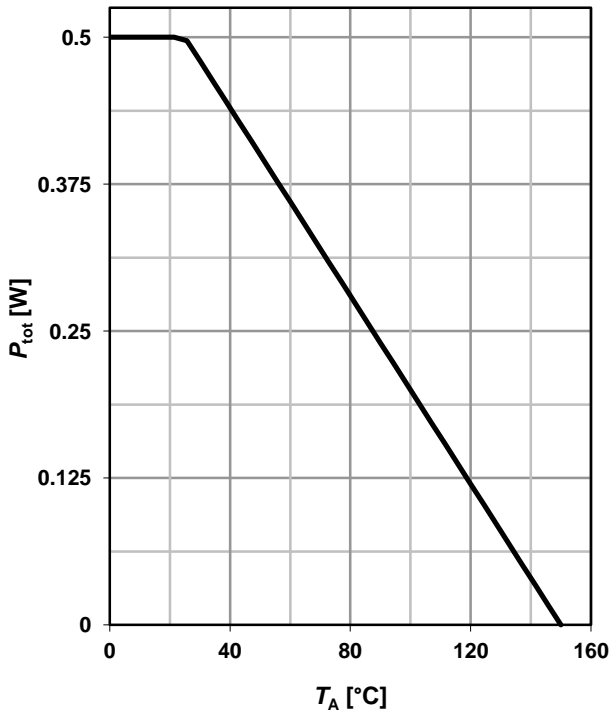
Gate to source charge	Q_{gs}	$V_{DD}=10\text{ V}, I_D=1.4\text{ A},$ $V_{GS}=0\text{ to }2.5\text{ V}$	-	0.2	-	nC
Gate to drain charge	Q_{gd}		-	0.2	-	
Gate charge total	Q_g		-	0.6	-	
Gate plateau voltage	$V_{plateau}$		-	1.6	-	V

Reverse Diode

Diode continuous forward current	I_S	$T_A=25\text{ }^\circ\text{C}$	-	-	0.5	A
Diode pulse current	$I_{S,pulse}$		-	-	6	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=1.4\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.87	1.1	V
Reverse recovery time	t_{rr}	$V_R=10\text{ V}, I_F=1.4\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	8.1	-	ns
Reverse recovery charge	Q_{rr}		-	1.4	-	nC

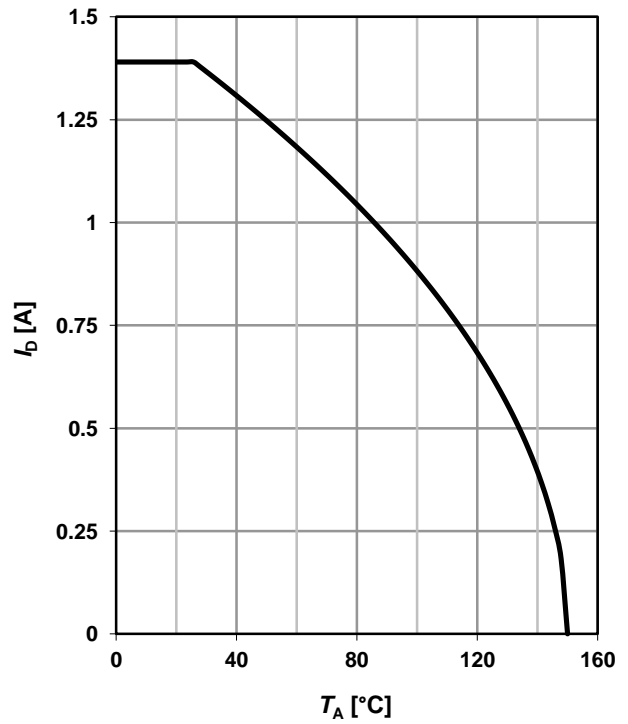
1 Power dissipation

$P_{tot}=f(T_A)$



2 Drain current

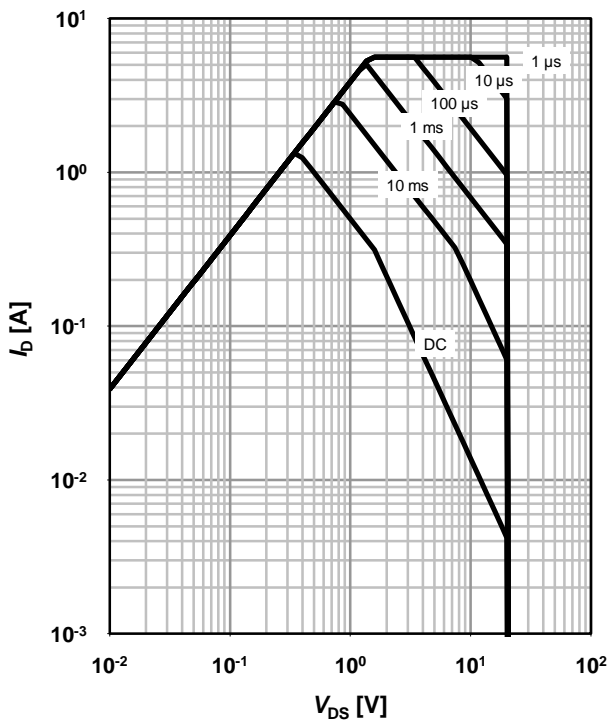
$I_D=f(T_A); V_{GS} \geq 2.5 V$



3 Safe operating area

$I_D=f(V_{DS}); T_A=25\text{ °C}; D=0$

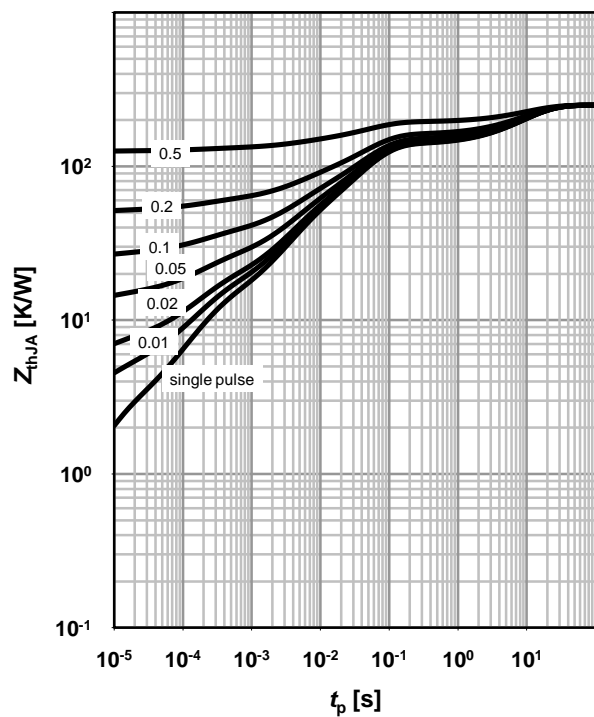
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJA}=f(t_p)$

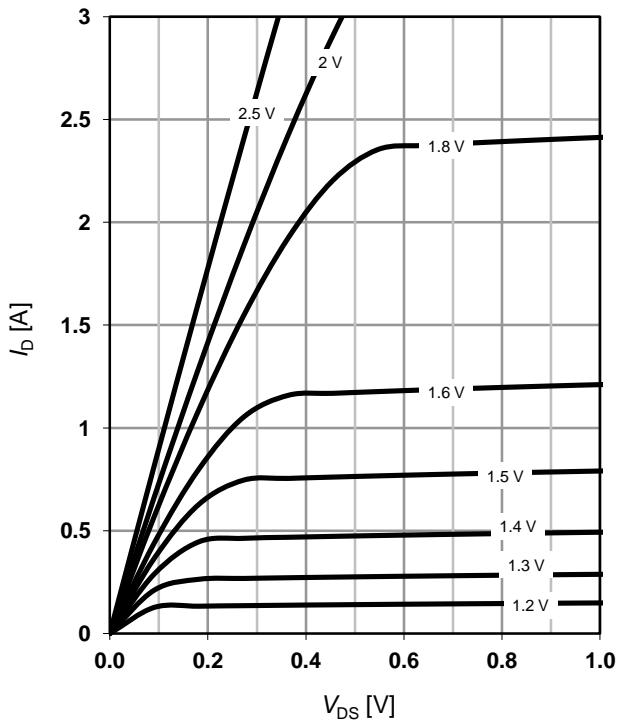
parameter: $D=t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ °C}$

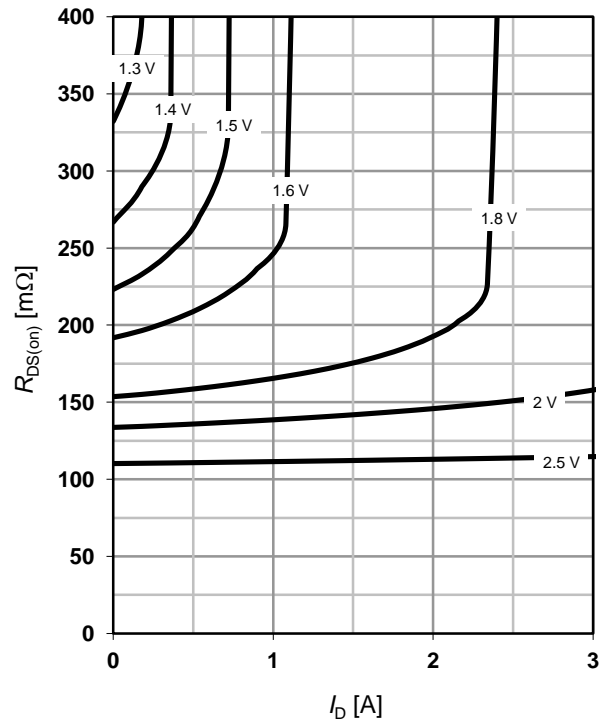
parameter: V_{GS}



6 Typ. drain-source on resistance

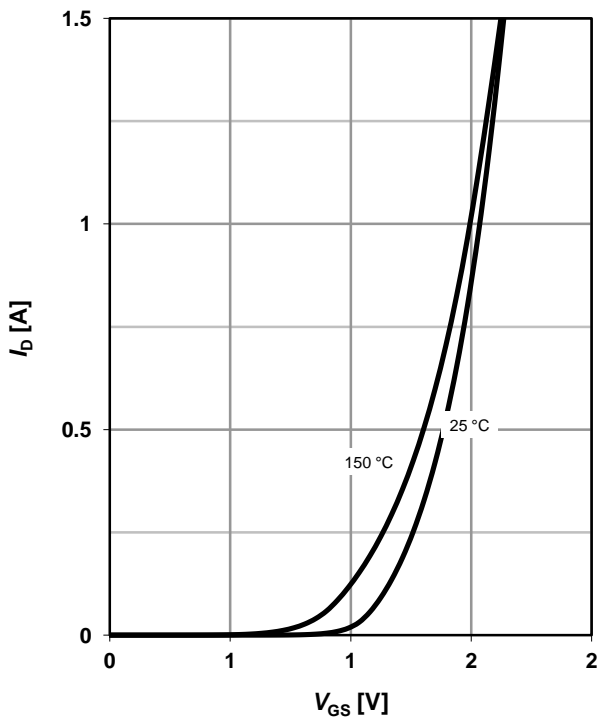
$R_{DS(on)} = f(I_D); T_j = 25\text{ °C}$

parameter: V_{GS}



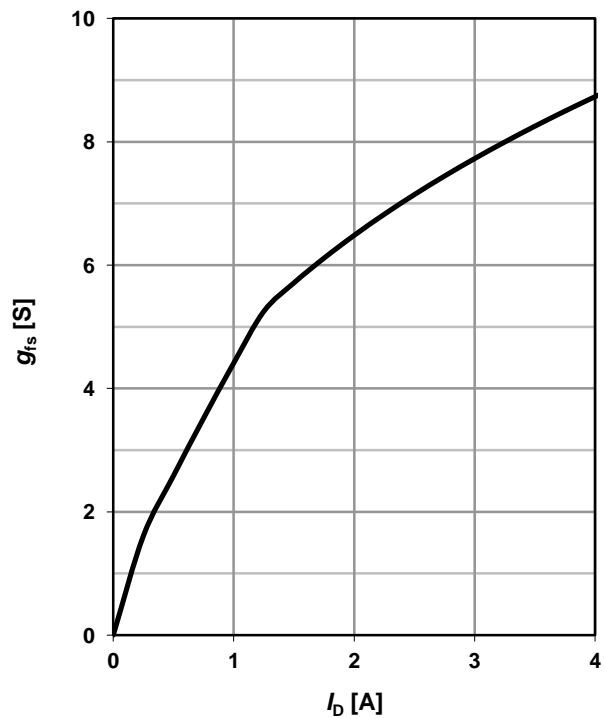
7 Typ. transfer characteristics

$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$



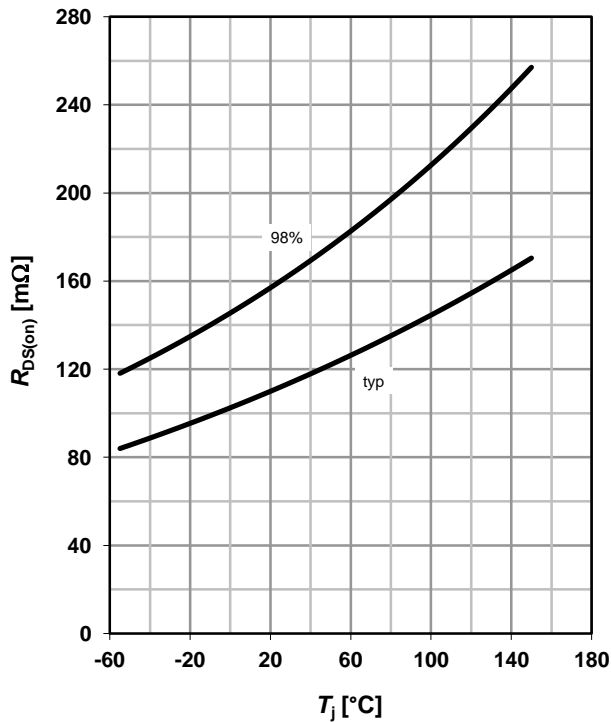
8 Typ. forward transconductance

$g_{fs} = f(I_D); T_j = 25\text{ °C}$



9 Drain-source on-state resistance

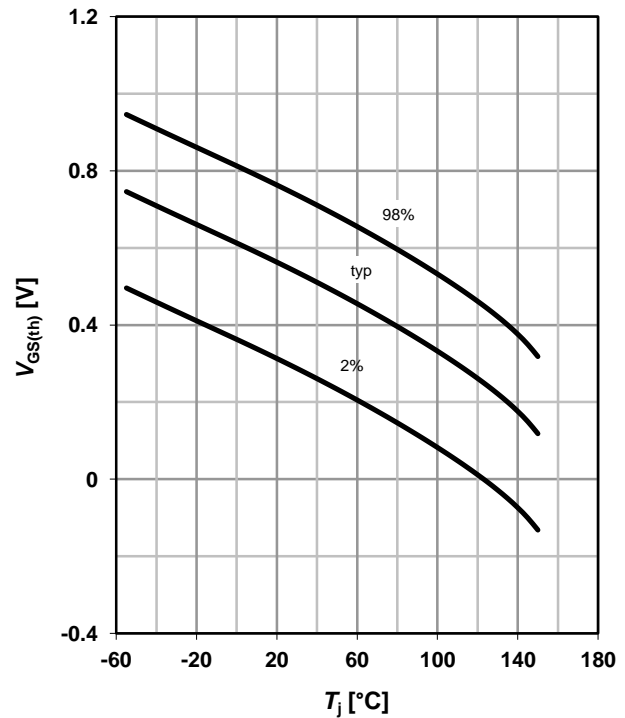
$R_{DS(on)}=f(T_j); I_D=1.4\text{ A}; V_{GS}=2.5\text{ V}$



10 Typ. gate threshold voltage

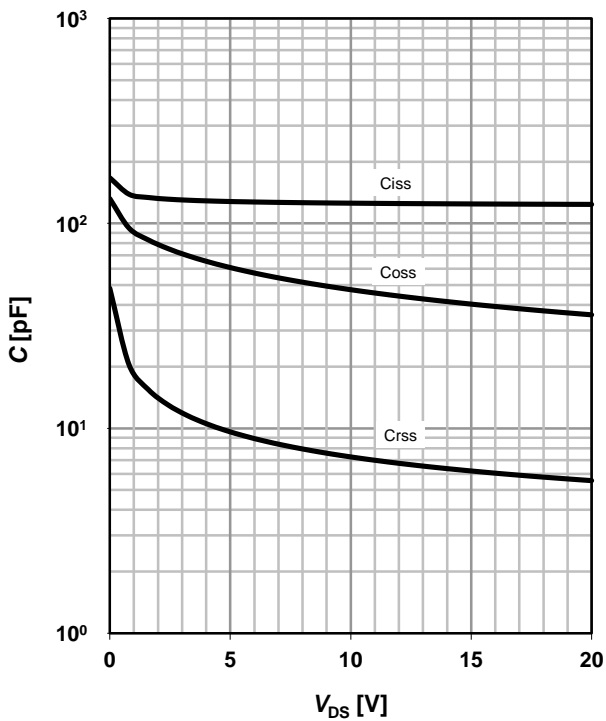
$V_{GS(th)}=f(T_j); V_{DS}=V_{GS}; I_D=3.7\text{ }\mu\text{A}$

parameter: I_D



11 Typ. capacitances

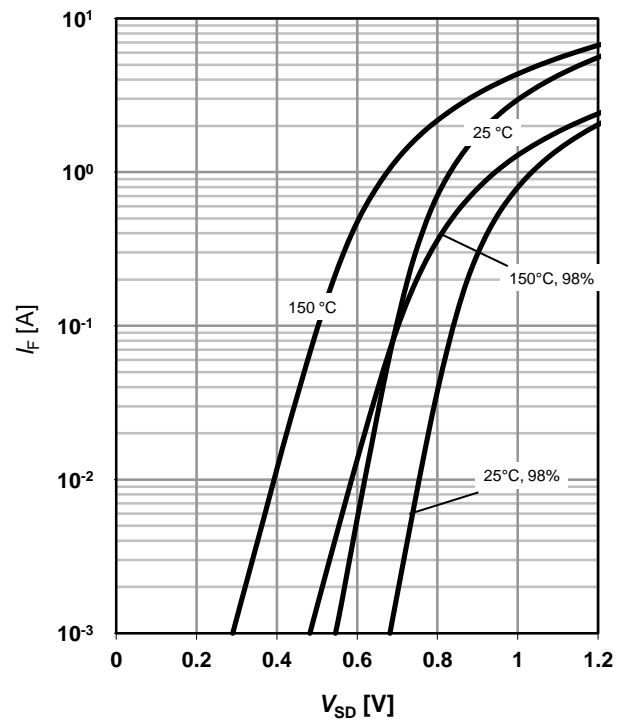
$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}; T_j=25^\circ\text{C}$



12 Forward characteristics of reverse diode

$I_F=f(V_{SD})$

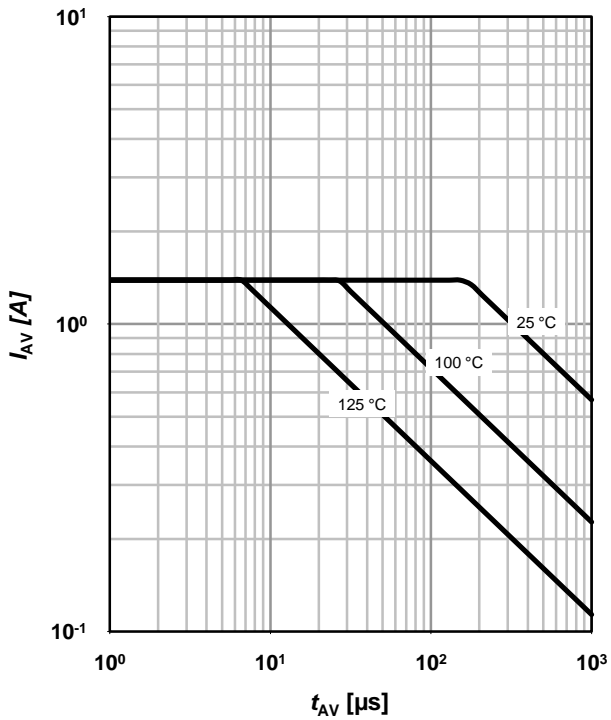
parameter: T_j



13 Avalanche characteristics

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

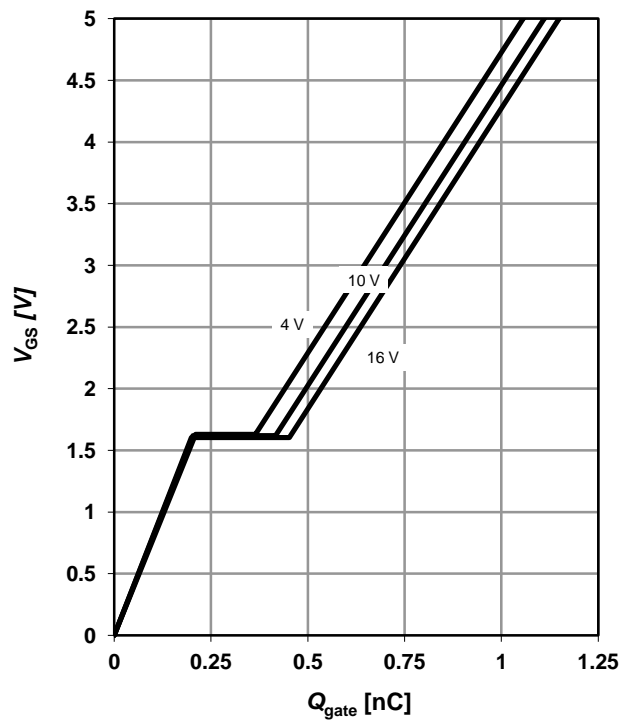
parameter: $T_{j(start)}$



14 Typ. gate charge

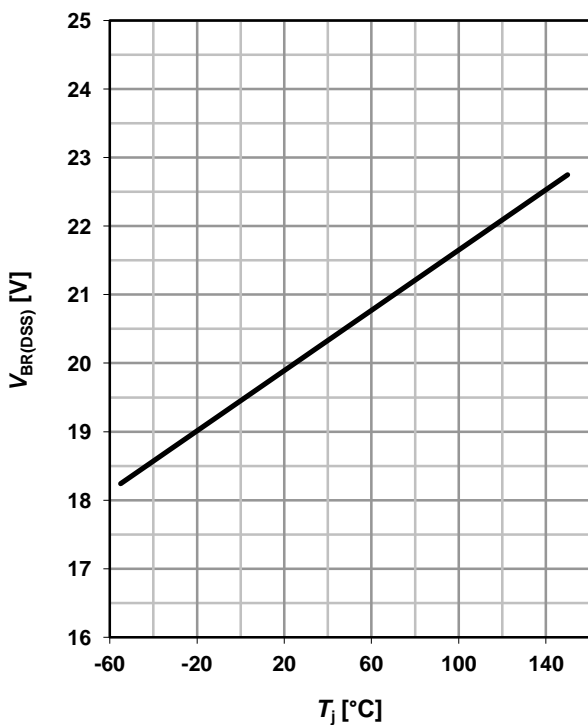
$V_{GS}=f(Q_{gate}); I_D=1.4 \text{ A pulsed}$

parameter: V_{DD}

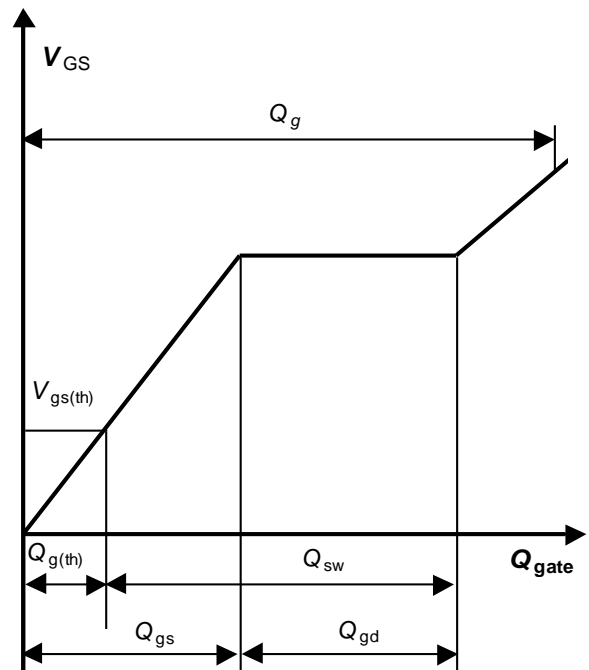


15 Drain-source breakdown voltage

$V_{BR(DSS)}=f(T_j); I_D=250 \mu\text{A}$

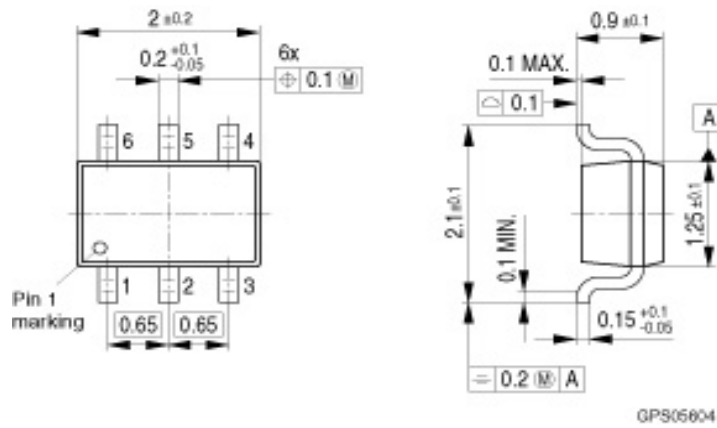


16 Gate charge waveforms



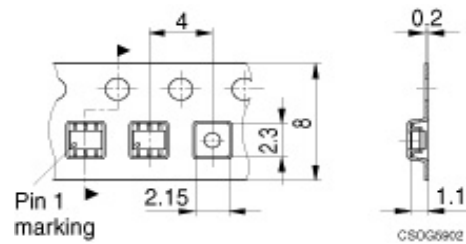
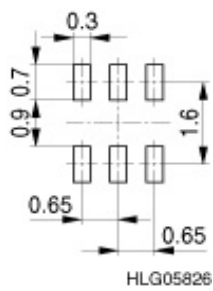
SOT363

Package Outline:



Reflow soldering:

Packing:



Dimensions in mm

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